

Data sheet acquired from Harris Semiconductor SCHS245R

September 1998 - Revised October 2000

Octal-Bus Transceiver, Three-State, Non-Inverting

Features

- · Buffered Inputs
- · Typical Propagation Delay
 - 4ns at $V_{CC} = 5V$, $T_A = 25^{\circ}C$, $C_L = 50pF$
- Exceeds 2kV ESD Protection per MIL-STD-883, Method 3015
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Speed of Bipolar FAST™/AS/S with Significantly Reduced Power Consumption
- Balanced Propagation Delays
- AC Types Feature 1.5V to 5.5V Operation and Balanced Noise Immunity at 30% of the Supply
- ±24mA Output Drive Current
 - Fanout to 15 FAST™ ICs
 - Drives 50Ω Transmission Lines

Description

The 'AC245 and 'ACT245 are octal-bus transceivers that utilize Advanced CMOS Logic technology. They are non-inverting three-state bidirectional transceiver-buffers intended for two-way transmission from "A" bus to "B" bus or "B" bus to "A". The logic level present on the direction input (DIR) determines the data direction. When the output enable input $(\overline{\text{OE}})$ is HIGH, the outputs are in the high-impedance state.

Ordering Information

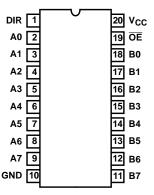
PART NUMBER	TEMP. RANGE (^O C)	PACKAGE
CD54AC245F3A	-55 to 125	20 Ld CERDIP
CD74AC245E	-55 to 125	20 Ld PDIP
CD74AC245M	-55 to 125	20 Ld SOIC
CD74AC245SM	-55 to 125	20 Ld SSOP
CD54ACT245F3A	-55 to 125	20 Ld CERDIP
CD74ACT245E	-55 to 125	20 Ld PDIP
CD74ACT245M	-55 to 125	20 Ld SOIC
CD74ACT245SM	-55 to 125	20 Ld SSOP

NOTES:

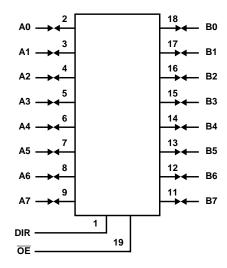
- 1. When ordering, use the entire part number. Add the suffix 96 to obtain the variant in the tape and reel.
- Wafer and die for this part number is available which meets all electrical specifications. Please contact your local TI sales office or customer service for ordering information.

Pinout

CD54AC245, CD54ACT245 (CERDIP) CD74AC245, CD74ACT245 (PDIP, SOIC, SSOP) TOP VIEW



Functional Diagram



TRUTH TABLE

CONTRO	L INPUTS	
ŌĒ	DIR	OPERATION
L	L	B Data to A Bus
L	Н	A Data to B Bus
Н	Х	Isolation

H = High Level, L = Low Level, X = Irrelevant To prevent excess currents in the High-Z (isolation) modes, all I/O terminals should be terminated with $10k\Omega$ to $1M\Omega$ resistors.

Absolute Maximum Ratings DC Supply Voltage, V_{CC} -0.5V to 6V DC Input Diode Current, I_{IK}

DC Output Diode Current, I_{OK}

DC Output Source or Sink Current per Output Pin, IO

DC V_{CC} or Ground Current, I_{CC or} I_{GND} (Note 3) ±100mA

Operating Conditions

Temperature Range, T _A 55°C to 125°C
Supply Voltage Range, V _{CC} (Note 4)
AC Types
ACT Types
DC Input or Output Voltage, V _I , V _O 0V to V _{CC}
Input Rise and Fall Slew Rate, dt/dv
AC Types, 1.5V to 3V 50ns (Max)
AC Types, 3.6V to 5.5V
ACT Types, 4.5V to 5.5V

Thermal Information

Thermal Resistance (Typical, Note 5)	θ _{JA} (°C/W)
E Package	69
M Package	58
SM Package	70
Maximum Junction Temperature (Plastic Package)	150 ^o C
Maximum Storage Temperature Range6	S5 ^o C to 150 ^o C
Maximum Lead Temperature (Soldering 10s)	300°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTES:

- 3. For up to 4 outputs per device, add ± 25 mA for each additional output.
- 4. Unless otherwise specified, all voltages are referenced to ground.
- 5. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

		I	TEST CONDITIONS		V _{CC} 25°		-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
AC TYPES											
High Level Input Voltage	V _{IH}	-	-	1.5	1.2	-	1.2	-	1.2	-	V
				3	2.1	-	2.1	-	2.1	-	V
				5.5	3.85	-	3.85	-	3.85	-	V
Low Level Input Voltage	V _{IL}	-	-	1.5	-	0.3	-	0.3	-	0.3	V
				3	-	0.9	-	0.9	-	0.9	V
				5.5	-	1.65	-	1.65	-	1.65	V
High Level Output Voltage	V _{OH}	V _{IH} or V _{IL}	-0.05	1.5	1.4	-	1.4	-	1.4	-	V
			-0.05	3	2.9	-	2.9	-	2.9	-	V
			-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-4	3	2.58	-	2.48	-	2.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-			-	3.85	-	V

DC Electrical Specifications (Continued)

		1	TEST CONDITIONS V _{CC}		25°C		-40°C TO 85°C		-55°C TO 125°C		
PARAMETER	SYMBOL	V _I (V)	I _O (mA)	(V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
Low Level Output Voltage	V_{OL}	V _{IH} or V _{IL}	0.05	1.5	-	0.1	-	0.1	-	0.1	V
			0.05	3	-	0.1	-	0.1	-	0.1	V
			0.05	4.5	-	0.1	-	0.1	-	0.1	V
			12	3	-	0.36	-	0.44	-	0.5	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I _I	V _{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	μА
Three-State Leakage Current	I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND	-	5.5	-	±0.5	-	±5	-	±10	μА
Quiescent Supply Current MSI	Icc	V _{CC} or GND	0	5.5	-	8	-	80	-	160	μА
ACT TYPES		•									
High Level Input Voltage	V _{IH}	-	-	4.5 to 5.5	2	-	2	-	2	-	V
Low Level Input Voltage	V _{IL}	-	-	4.5 to 5.5	-	0.8	-	0.8	-	0.8	V
High Level Output Voltage	V _{OH}	V _{IH} or V _{IL}	-0.05	4.5	4.4	-	4.4	-	4.4	-	V
			-24	4.5	3.94	-	3.8	-	3.7	-	V
			-75 (Note 6, 7)	5.5	-	-	3.85	-	-	-	V
			-50 (Note 6, 7)	5.5	-	-	-	-	3.85	-	V
Low Level Output Voltage	V_{OL}	V _{IH} or V _{IL}	0.05	4.5	-	0.1	-	0.1	-	0.1	V
			24	4.5	-	0.36	-	0.44	-	0.5	V
			75 (Note 6, 7)	5.5	-	-	-	1.65	-	-	V
			50 (Note 6, 7)	5.5	-	-	-	-	-	1.65	V
Input Leakage Current	I _I	V _{CC} or GND	-	5.5	-	±0.1	-	±1	-	±1	μА
Three-State or Leakage Current	I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND	-	5.5	-	±0.5	-	±5	-	±10	μА
Quiescent Supply Current MSI	Icc	V _{CC} or GND	0	5.5	-	8	-	80	-	160	μА
Additional Supply Current per Input Pin TTL Inputs High 1 Unit Load	Δl _{CC}	V _{CC} -2.1	-	4.5 to 5.5	-	2.4	-	2.8	-	3	mA

NOTES:

- 6. Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
- 7. Test verifies a minimum 50Ω transmission-line-drive capability at 85° C, 75Ω at 125° C.

ACT Input Load Table

INPUT	UNIT LOAD
An, Bn	0.83
ŌĒ	0.64
DIR	0.25

NOTE: Unit load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 2.4mA max at 25°C.

Switching Specifications Input t_r , $t_f = 3ns$, $C_L = 50pF$ (Worst Case)

			-40	OC TO 85	°C	-55	OC TO 12	5°C	
PARAMETER	SYMBOL	V _{CC} (V)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
AC TYPES		•		•			•	•	•
Propagation Delay,	t _{PLH} , t _{PHL}	1.5	-	-	96	-	-	106	ns
Data to Output		3.3 (Note 9)	3.2	-	10.8	3	-	11.9	ns
		5 (Note 10)	2.2	-	7.7	2.1	-	8.5	ns
Propagation Delay,	t _{PLZ} , t _{PHZ}	1.5	-	-	159	-	-	175	ns
Output Disable to Output		3.3	4.7	-	15.9	4.4	-	17.5	ns
		5	3.7	-	12.7	3.5	-	14	ns
Propagation Delay,	t _{PZL} , t _{PZH}	1.5	-	-	159	-	-	175	ns
Output Enable to Output		3.3	5.6	-	19	5.3	-	21	ns
		5	3.7	-	12.7	3.5	-	14	ns
Minimum (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Figure 1	5	-	4 at 25°C	-	-	4 at 25 ^o C	-	V
Maximum (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Figure 1	5	-	1 at 25 ⁰ C	-	-	1 at 25 ⁰ C	-	V
Three-State Output Capacitance	CO	-	-	15	-	-	15	-	pF
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C _{PD} (Note 11)	-	-	57	-	-	57	-	pF
ACT TYPES					<u>I</u>			<u> </u>	
Propagation Delay, Data to Output	t _{PLH} , t _{PHL}	5 (Note 10)	2.7	-	9.1	2.5	-	10	ns
Propagation Delay, Output Disable to Output	t _{PLZ} , t _{PHZ}	5	3.7		12.7	3.5		14	ns
Propagation Delay, Output Enable to Output	t _{PZL} , t _{PZH}	5	3.8		13.1	3.6		14.4	ns
Minimum (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Figure 1	5	-	4 at 25°C	-	-	4 at 25 ^o C	-	V
Maximum (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Figure 1	5	-	1 at 25 ^o C	-	-	1 at 25 ^o C	-	V

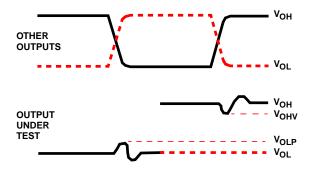
Switching Specifications Input t_r , $t_f = 3ns$, $C_L = 50pF$ (Worst Case) (Continued)

			-40°C TO 85°C		-55°C TO 125°C				
PARAMETER	SYMBOL	V _{CC} (V)	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Three-State Output Capacitance	co	-	-	15	-	-	15	-	pF
Input Capacitance	Cl	-	-	-	10	-	-	10	pF
Power Dissipation Capacitance	C _{PD} (Note 11)	1	ı	57	ı	ı	57	1	pF

NOTES:

- 8. Limits tested 100%
- 9. 3.3V Min is at 3.6V, Max is at 3V.
- 10. 5V Min is at 5.5V, Max is at 4.5V.
- 11. C_{PD} is used to determine the dynamic power consumption per channel.

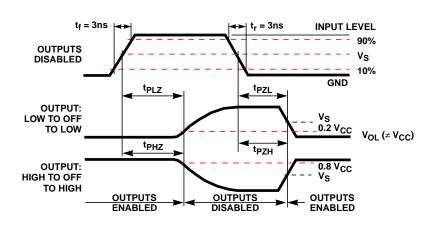
AC: $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$ ACT: $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$ where f_i = input frequency, C_L = output load capacitance, V_{CC} = supply voltage.

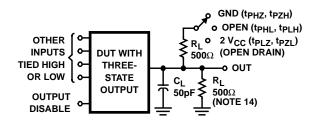


NOTES:

- 12. Input pulses have the following characteristics: PRR \leq 1MHz, t_r = 3ns, SKEW 1ns.
- 13. R.F. fixture with 700MHz design rules required. IC should be soldered into test board and bypassed with 0.1µF capacitor. Scope and probes require 700MHz bandwidth.

FIGURE 1. SIMULTANEOUS SWITCHING TRANSIENT WAVEFORMS





NOTE:

14. For AC Series only: When V_{CC} = 1.5V, R_L = 1k $\!\Omega.$

FIGURE 2. THREE-STATE PROPAGATION DELAY TIMES AND TEST CIRCUIT

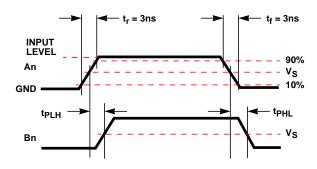
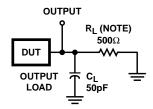


FIGURE 3. PROPAGATION DELAY TIMES



NOTE: For AC Series Only: When V_{CC} = 1.5V, R_L = 1k Ω .

	AC	ACT
Input Level	V _{CC}	3V
Input Switching Voltage, V _S	0.5 V _{CC}	1.5V
Output Switching Voltage, V _S	0.5 V _{CC}	0.5 V _{CC}

FIGURE 4. PROPAGATION DELAY TIMES





i.com 28-Feb-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finisl	n MSL Peak Temp ⁽³⁾
CD54AC245F3A	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
CD54ACT245F3A	ACTIVE	CDIP	J	20	1	None	Call TI	Level-NC-NC-NC
CD74AC245E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74AC245M	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74AC245M96	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74AC245SM	OBSOLETE	SSOP	DB	20		Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74AC245SM96	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT245E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD74ACT245M	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT245M96	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT245SM	OBSOLETE	SSOP	DB	20		Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
CD74ACT245SM96	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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